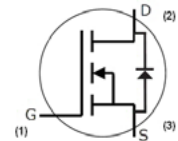


E3M0280090D

Silicon Carbide Power MOSFET
E-Series Automotive
N-Channel Enhancement Mode



TO-247-3



Package Types: TO 247-3
PN's: E3M0280090D

Features

- 900 V SiC MOSFET technology
- High blocking voltage with low on-resistance
- High speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Halogen free, RoHS compliant
- Automotive qualified (AEC-Q101) and PPAP capable

Wolfspeed, Inc. is in the process of rebranding its products and related materials pursuant to the entity name change from Cree, Inc. to Wolfspeed, Inc. During this transition period, products received may be marked with either the Cree name and/or logo or the Wolfspeed name and/or logo.

Applications

- Automotive EV battery chargers
- Renewable energy
- High voltage DC/DC converters
- Telecom power supplies

Benefits

- Higher system efficiency
- Reduced cooling requirements
- Increased power density
- Increased system switching frequency

Maximum Ratings ($T_c = 25^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Value	Unit	Test Conditions	Note
Drain-Source Voltage	V_{DSmax}	900	V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
Gate-Source Voltage	V_{GSmax}	-8/+18			Note: 1
Gate-Source Voltage (Recommended operating values)	V_{GSop}	-4/+15			Note: 2
Continuous Drain Current	I_D	11.5	A	$V_{GS} = 15\text{ V}, T_c = 25^\circ\text{C}$	Fig. 19
		7.5			$V_{GS} = 15\text{ V}, T_c = 100^\circ\text{C}$
Pulsed Drain Current	$I_{D(pulse)}$	22		Pulse Width t_p Limited by T_{jmax}	Fig. 22
Power Dissipation	P_D	54	W	$T_c = 25^\circ\text{C}, T_j = 150^\circ\text{C}$	Fig. 20
Operating Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$		
Solder Temperature	T_L	260		1.6 mm (0.063") from Case for 10s	
Mounting Torque	M_d	1	Nm lbf-in	M3 or 6-32 Screw	
		8.8			

Note (1): When using MOSFET Body Diode $V_{GSmax} = -4\text{V}/+18\text{V}$.

Note (2): MOSFET can also safely operate at $0/+15\text{ V}$.


Electrical Characteristics ($T_C = 25\text{ }^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Note
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	900				$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
Gate Threshold Voltage	$V_{GS(th)}$	1.7	2.1	3.5	V	$V_{DS} = V_{GS}, I_D = 1.2\text{ mA}$	Fig. 11
			1.6			$V_{DS} = V_{GS}, I_D = 1.2\text{ mA}, T_J = 150\text{ }^\circ\text{C}$	
Zero Gate Voltage Drain Current	I_{DSS}		1	100	μA	$V_{DS} = 900\text{ V}, V_{GS} = 0\text{ V}$	
Gate-Source Leakage Current	I_{GSS}		10	250	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
Drain-Source On-State Resistance	$R_{DS(on)}$		280	364	m Ω	$V_{GS} = 15\text{ V}, I_D = 7.5\text{ A}$	Fig. 4, 5, 6
			385			$V_{GS} = 15\text{ V}, I_D = 15\text{ A}, T_J = 150\text{ }^\circ\text{C}$	
Transconductance	g_{fs}		3.6		S	$V_{DS} = 15\text{ V}, I_{DS} = 7.5\text{ A}$	Fig. 7
			3.1			$V_{DS} = 15\text{ V}, I_{DS} = 7.5\text{ A}, T_J = 150\text{ }^\circ\text{C}$	
Input Capacitance	C_{iss}		150		pF	$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}$ $f = 1\text{ MHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
Output Capacitance	C_{oss}		20				
Reverse Transfer Capacitance	C_{rfs}		2				
C_{oss} Stored Energy	E_{oss}		4.5		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 7.5\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 220\text{ }\mu\text{H}, T_J = 150\text{ }^\circ\text{C}$	Fig. 16
Turn-On Switching Energy (Body Diode FWD)	E_{ON}		57				Fig. 26, 29 Note 3
Turn-Off Switching Energy (Body Diode FWD)	E_{OFF}		6				
Turn-On Delay Time	$t_{d(on)}$		26		ns	$V_{DD} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 7.5\text{ A}, R_{G(ext)} = 2.5\text{ }\Omega,$ Timing Relative to V_{DS} Inductive Load	Fig. 27, 29 Note 3
Rise Time	t_r		10				
Turn-Off Delay Time	$t_{d(off)}$		17.5				
Fall Time	t_f		7.5				
Internal Gate Resistance	$R_{G(int)}$		26		Ω	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
Gate to Source Charge	Q_{gs}		2.8		nC	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 7.5\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
Gate to Drain Charge	Q_{gd}		3.4				
Total Gate Charge	Q_g		9.5				



Reverse Diode Characteristics ($T_C = 25\text{ }^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Typ.	Max.	Unit	Test Conditions	Note
Diode Forward Voltage	V_{SD}	4.8		V	$V_{GS} = -4\text{ V}, I_{SD} = 4\text{ A}$	Fig. 8, 9, 10
		4.4			$V_{GS} = -4\text{ V}, I_{SD} = 4\text{ A}, T_J = 150\text{ }^\circ\text{C}$	
Continuous Diode Forward Current	I_S		9.6	A	$V_{GS} = -4\text{ V}, T_C = 25\text{ }^\circ\text{C}$	Note: 1
Diode Pulse Current	$I_{S, pulse}$		22		$V_{GS} = -4\text{ V}, \text{Pulse Width } t_p \text{ Limited by } T_{Jmax}$	Note: 1
Reverse Recovery Time	t_{rr}	20		ns	$V_{GS} = -4\text{ V}, I_{SD} = 4\text{ A}, V_R = 400\text{ V}$ $dif/dt = 800\text{ A}/\mu\text{s}, T_J = 150\text{ }^\circ\text{C}$	Note: 1
Reverse Recovery Charge	Q_{rr}	47		nC		
Peak Reverse Recovery Current	I_{rrm}	3.4		A		

Thermal Characteristics

Parameter	Symbol	Max.	Unit	Test Conditions	Note
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.3	$^\circ\text{C}/\text{W}$		Fig. 21
Thermal Resistance From Junction to Ambient	$R_{\theta JA}$	40			

Note (3): Turn-off and Turn-on switching energy and timing values measured using SiC MOSFET Body Diode.



Typical Performance

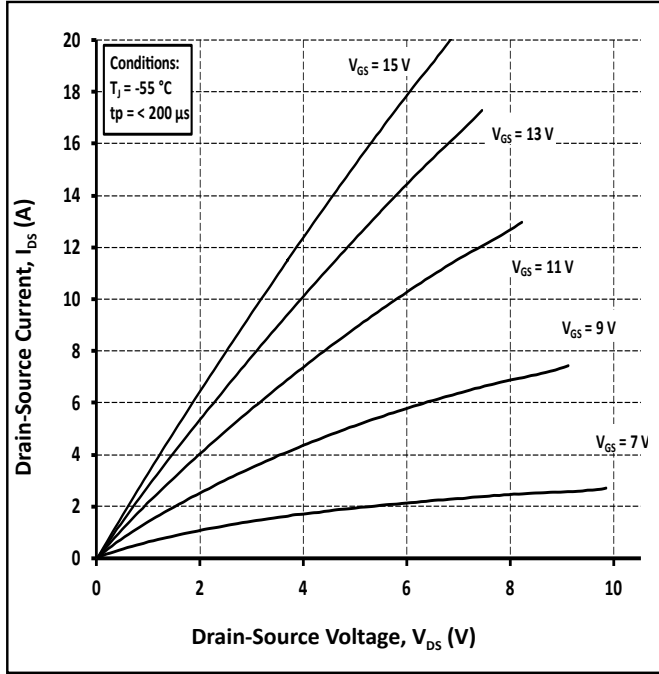


Figure 1. Output Characteristics $T_j = -55\text{ }^\circ\text{C}$

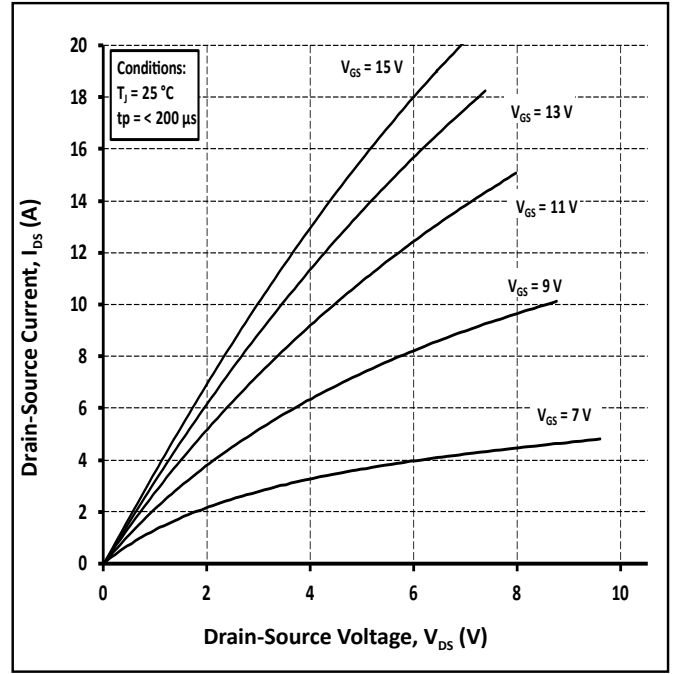


Figure 2. Output Characteristics $T_j = 25\text{ }^\circ\text{C}$

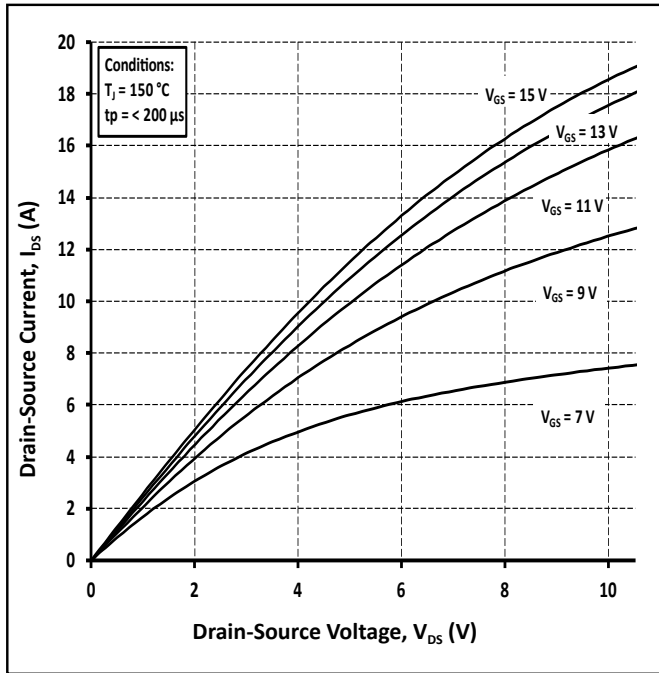


Figure 3. Output Characteristics $T_j = 150\text{ }^\circ\text{C}$

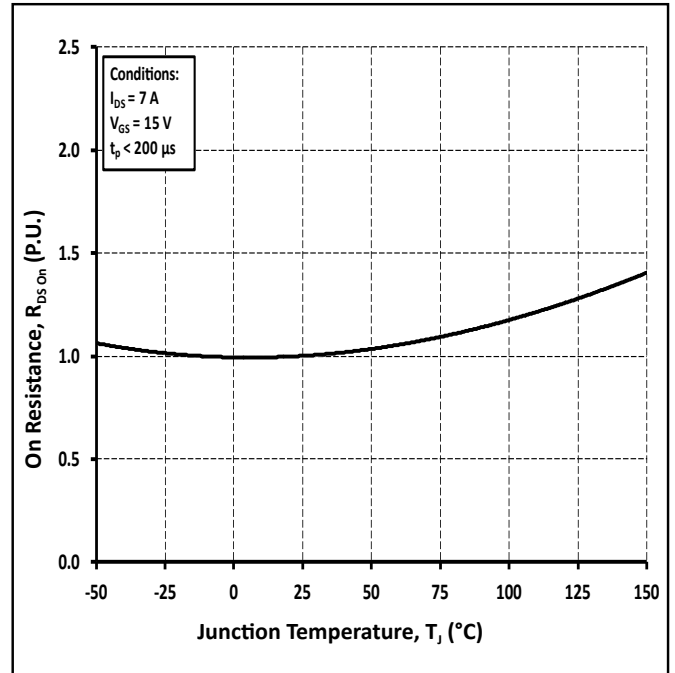


Figure 4. Normalized On-Resistance vs. Temperature



Typical Performance

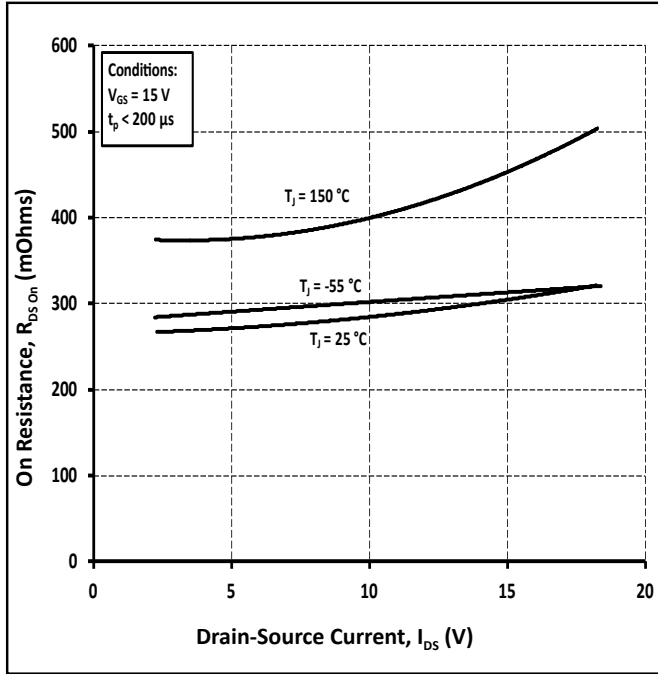


Figure 5. On-Resistance vs. Drain Current for Various Temperatures

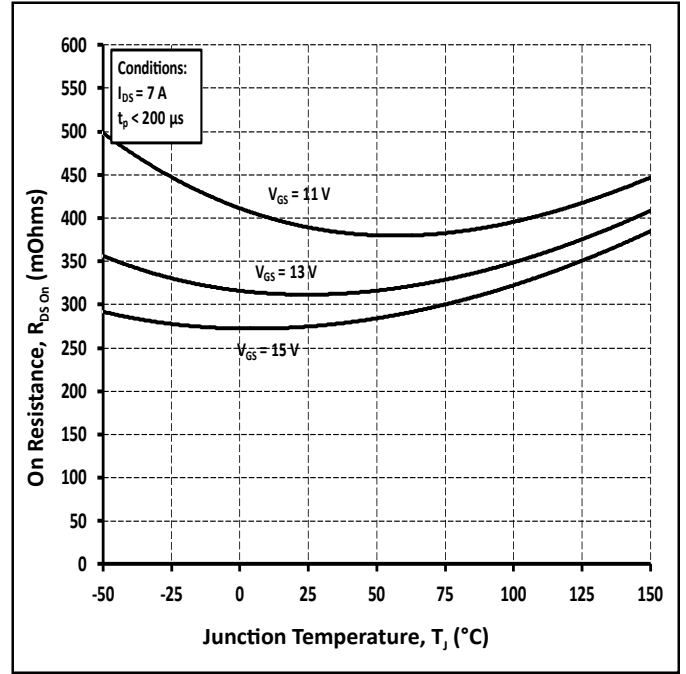


Figure 6. On-Resistance vs. Temperature for Various Gate Voltage

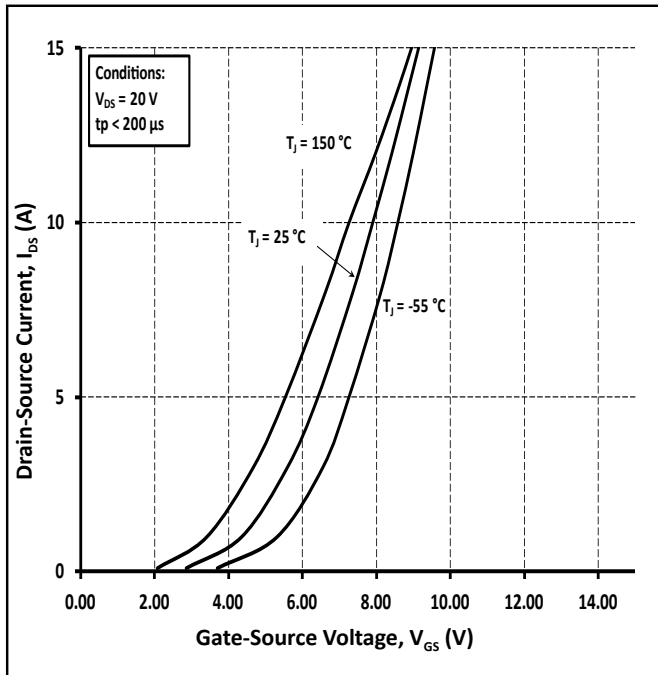


Figure 7. Transfer Characteristic for Various Junction Temperatures

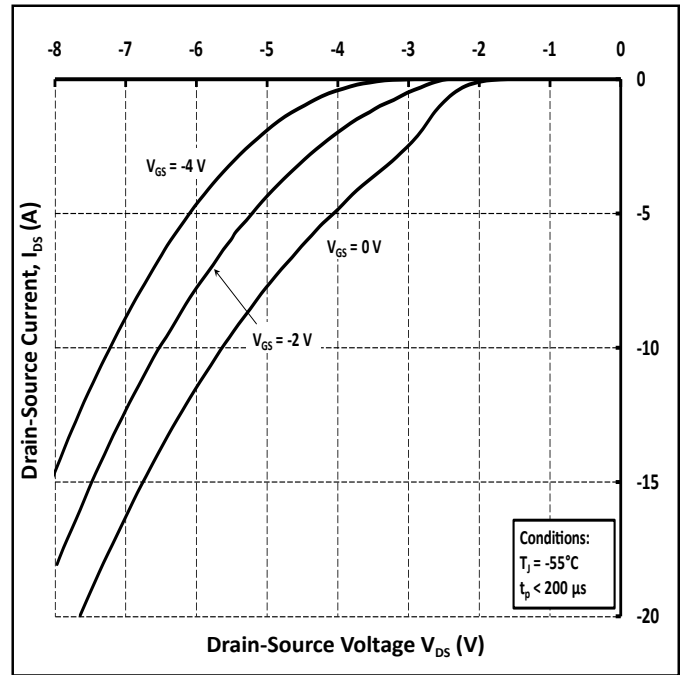


Figure 8. Body Diode Characteristic at -55 °C



Typical Performance

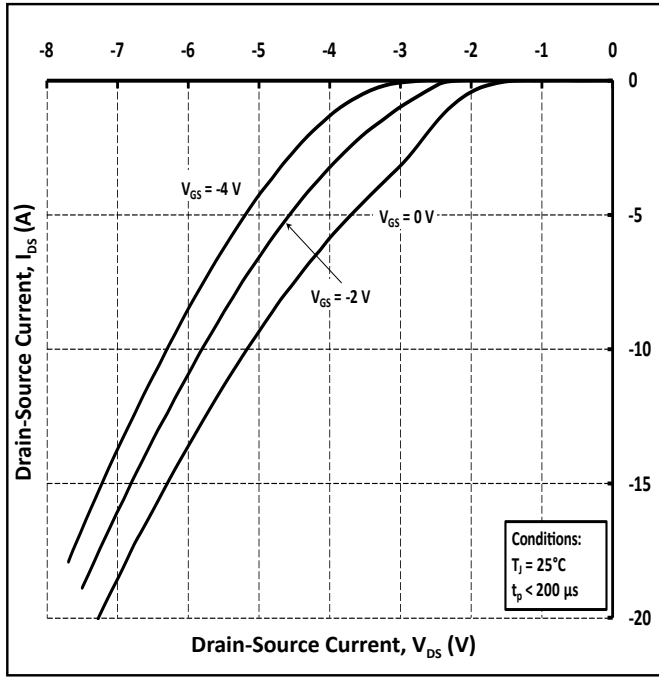


Figure 9. Body Diode Characteristic at 25 °C

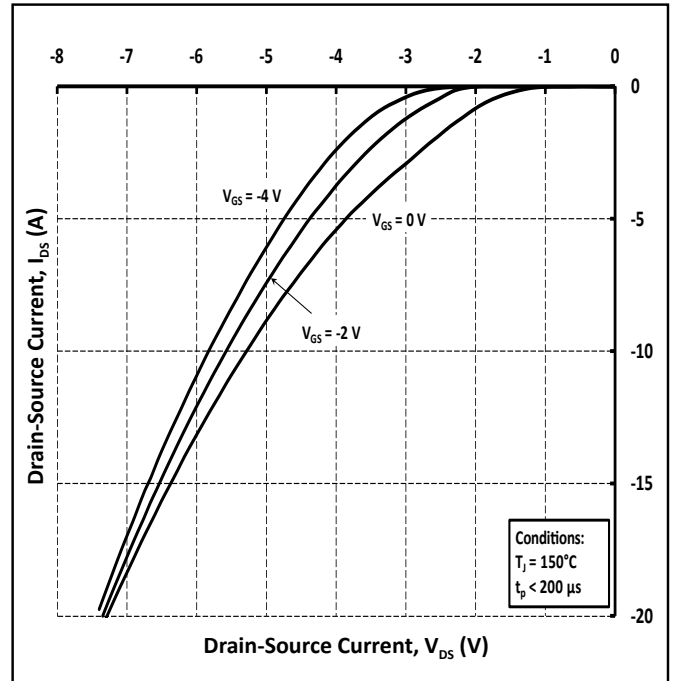


Figure 10. Body Diode Characteristic at 150 °C

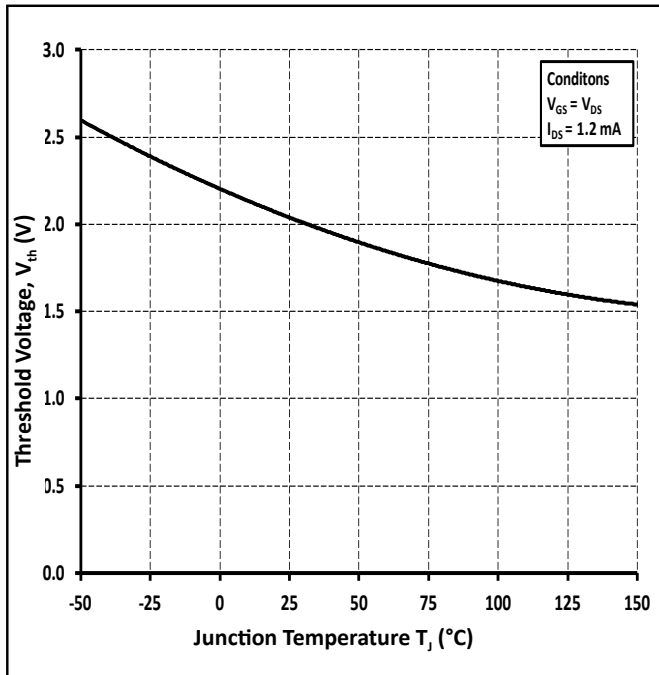


Figure 11. Threshold Voltage vs. Temperature

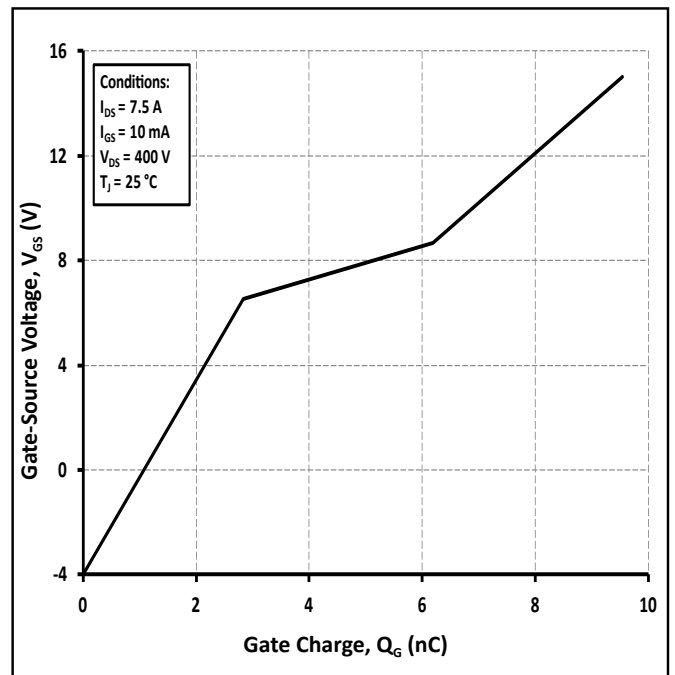


Figure 12. Gate Charge Characteristics



Typical Performance

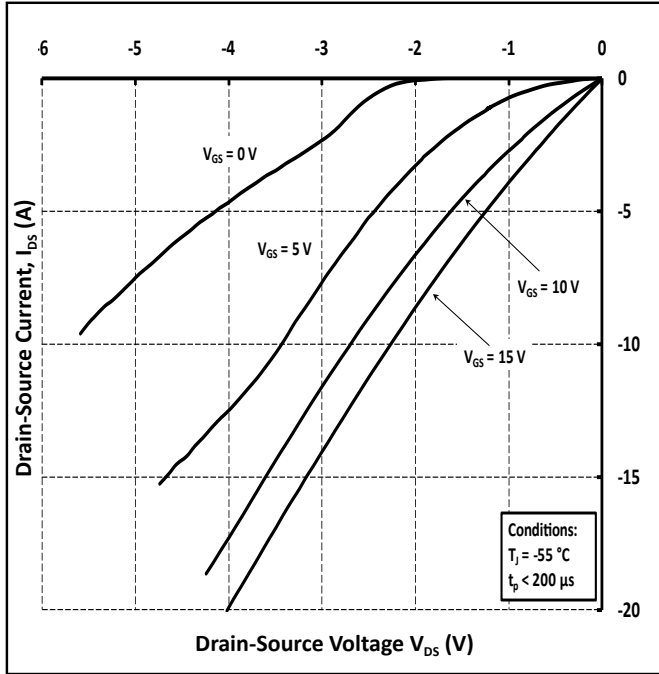


Figure 13. 3rd Quadrant Characteristic at -55 °C

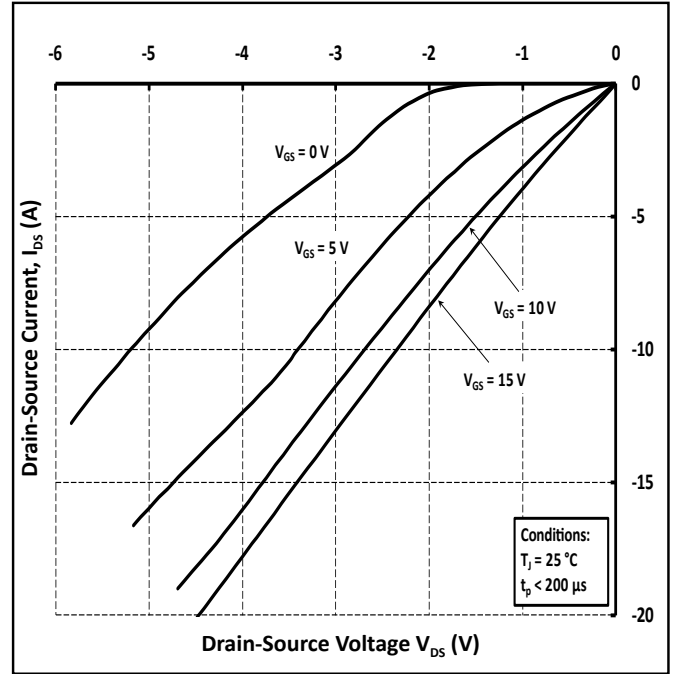


Figure 14. 3rd Quadrant Characteristic at 25 °C

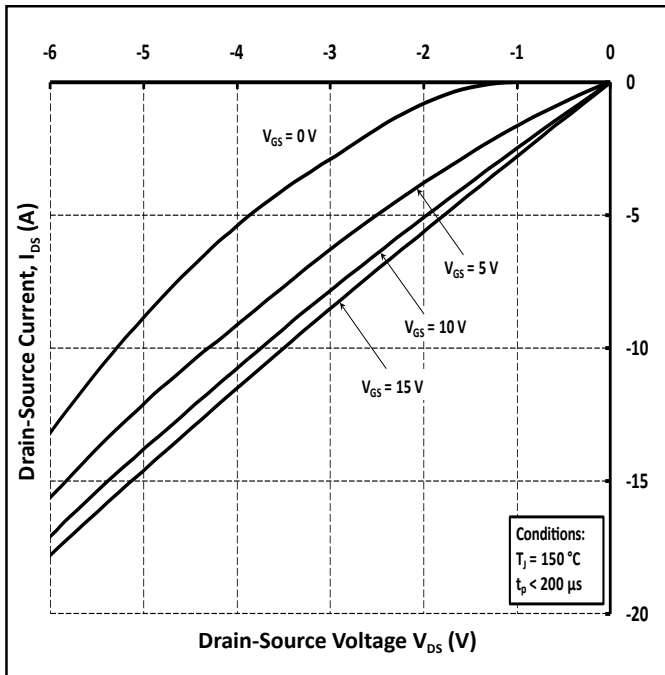


Figure 15. 3rd Quadrant Characteristic at 150 °C

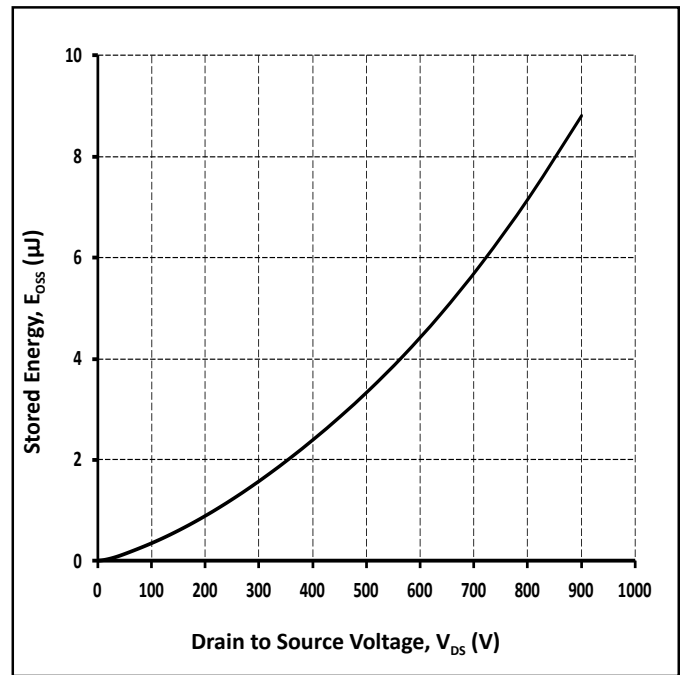


Figure 16. Output Capacitor Stored Energy



Typical Performance

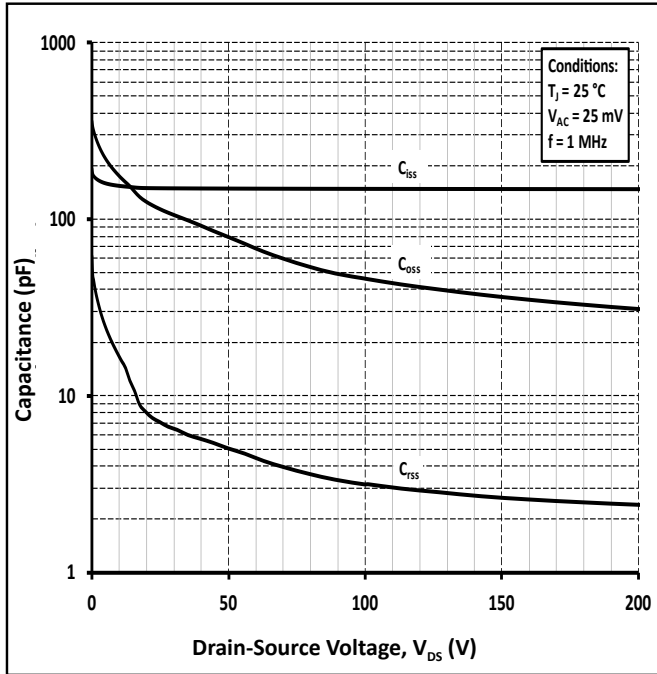


Figure 17. Capacitances vs. Drain-Source Voltage (0-200 V)

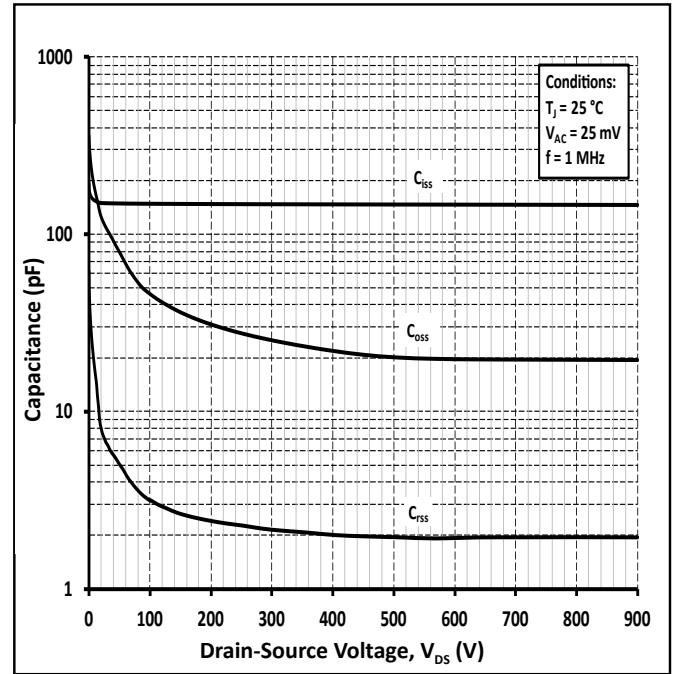


Figure 18. Capacitances vs. Drain-Source Voltage (0-900 V)

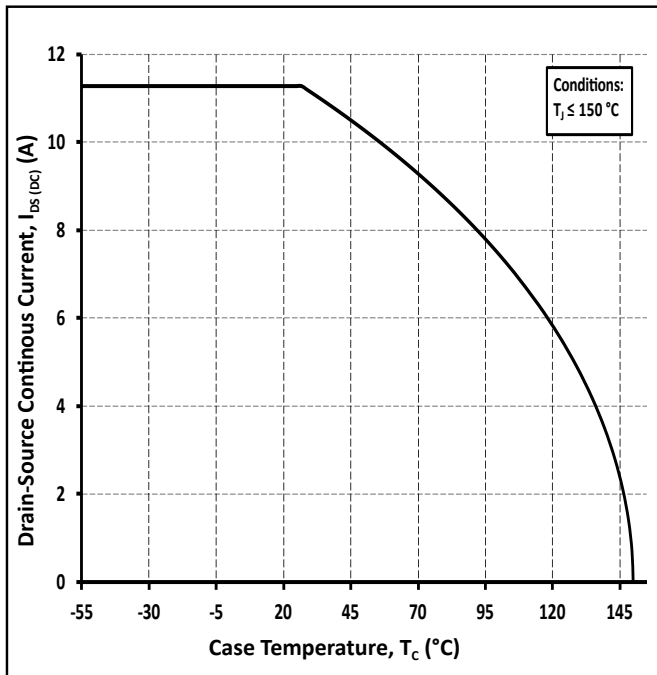


Figure 19. Continuous Drain Current Derating vs. Case Temperature

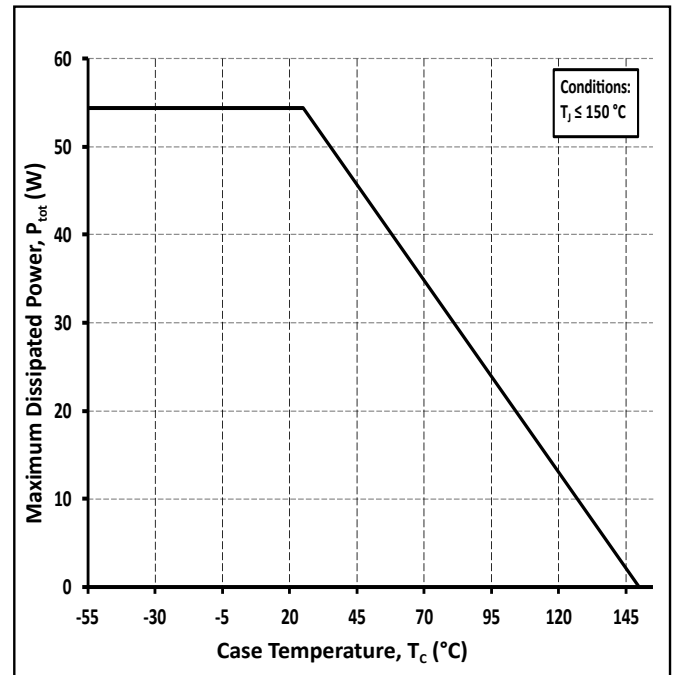


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature



Typical Performance

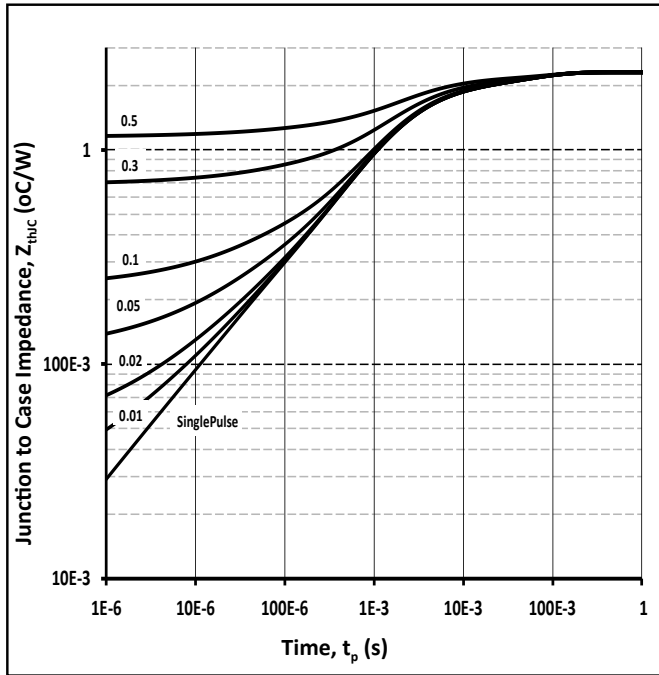


Figure 21. Transient Thermal Impedance (Junction - Case)

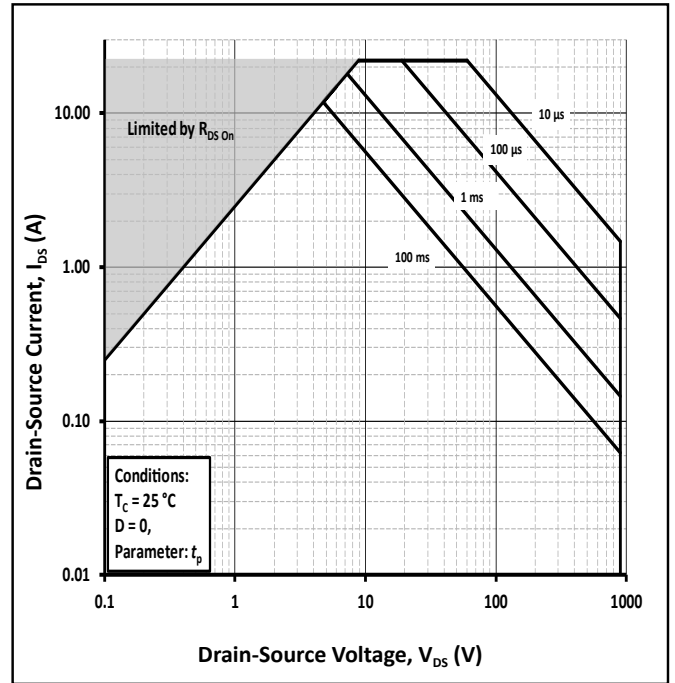


Figure 22. Safe Operating Area

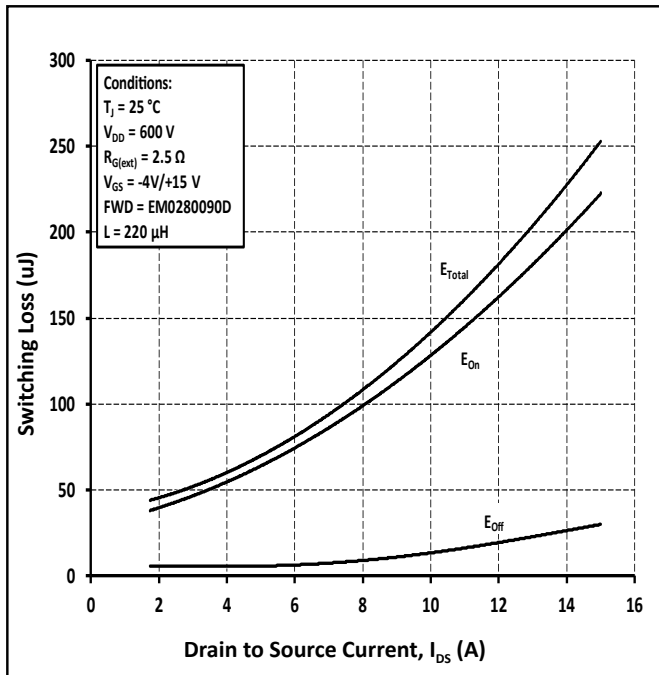


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600\text{ V}$)

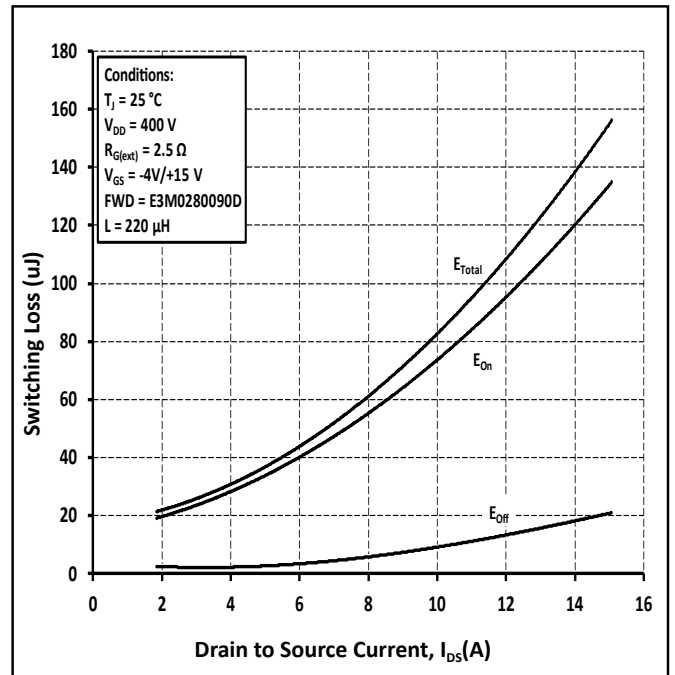


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 400\text{ V}$)



Typical Performance

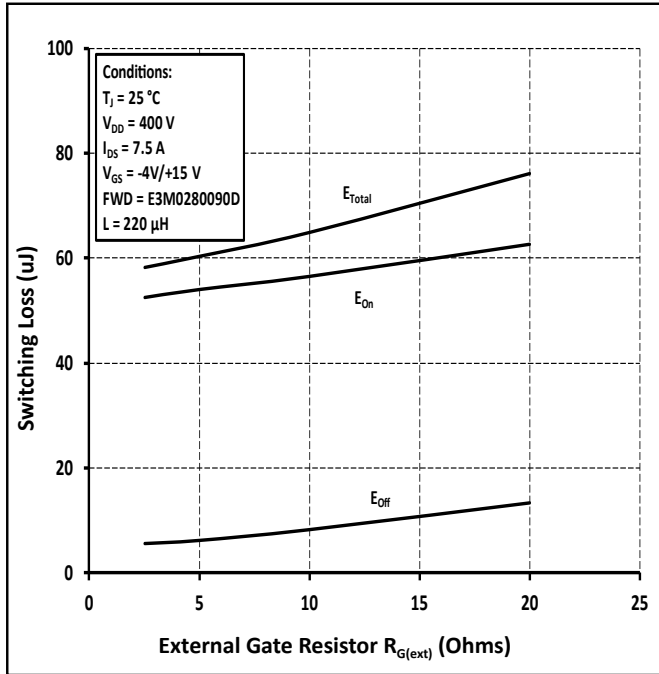


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

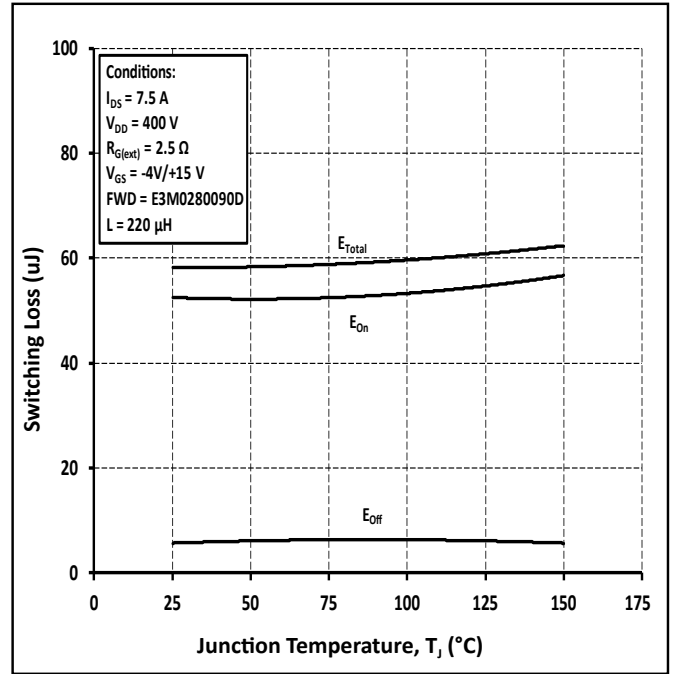


Figure 26. Clamped Inductive Switching Energy vs. Temperature

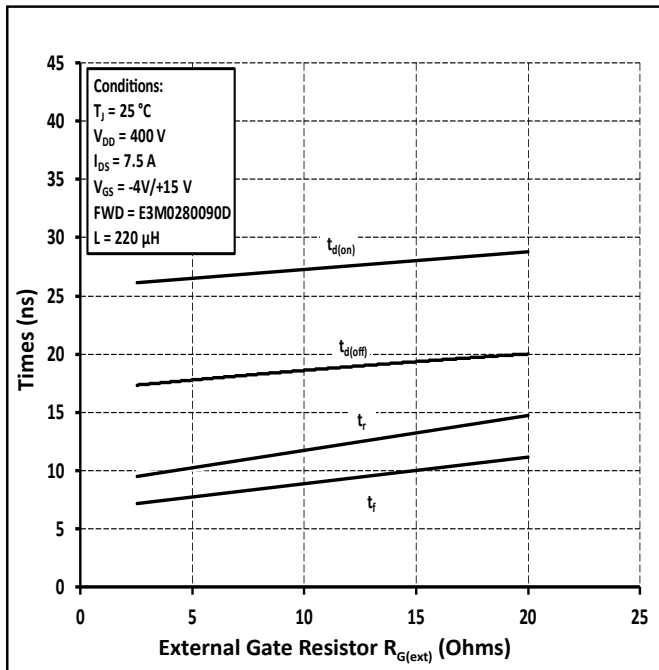


Figure 27. Switching Times vs. $R_{G(ext)}$

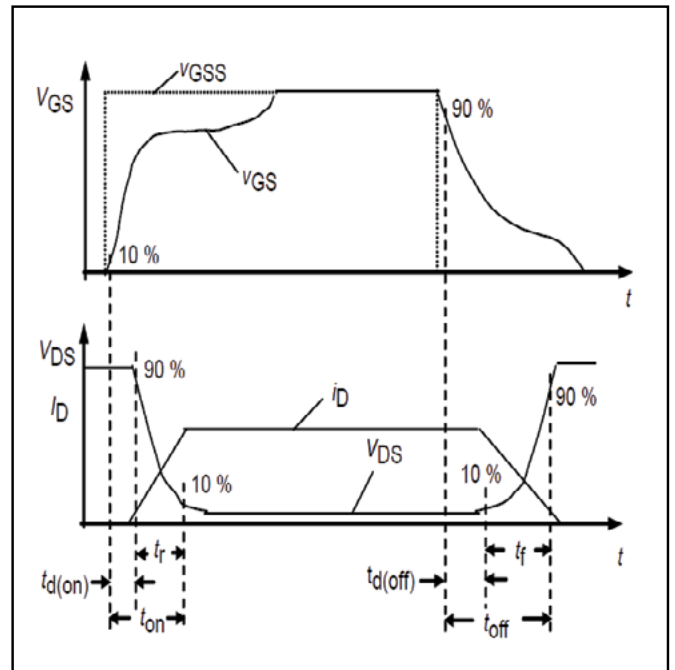


Figure 28. Switching Times Definition

Test Circuit Schematic

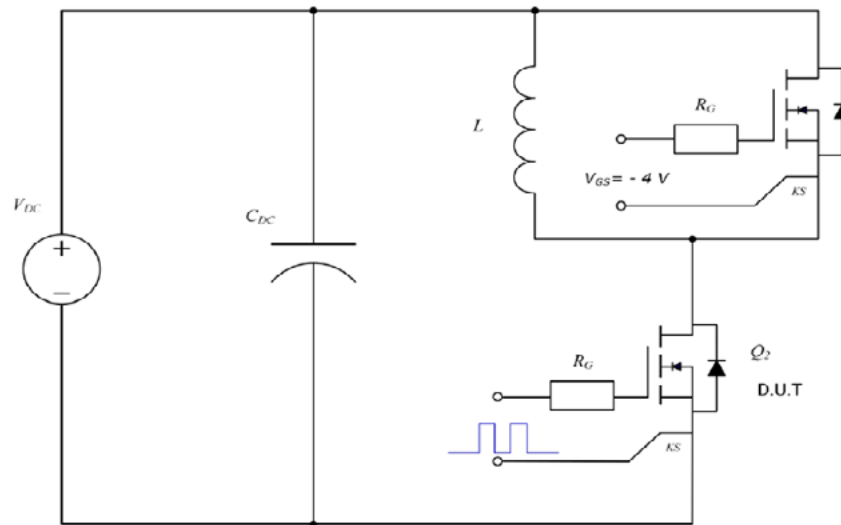


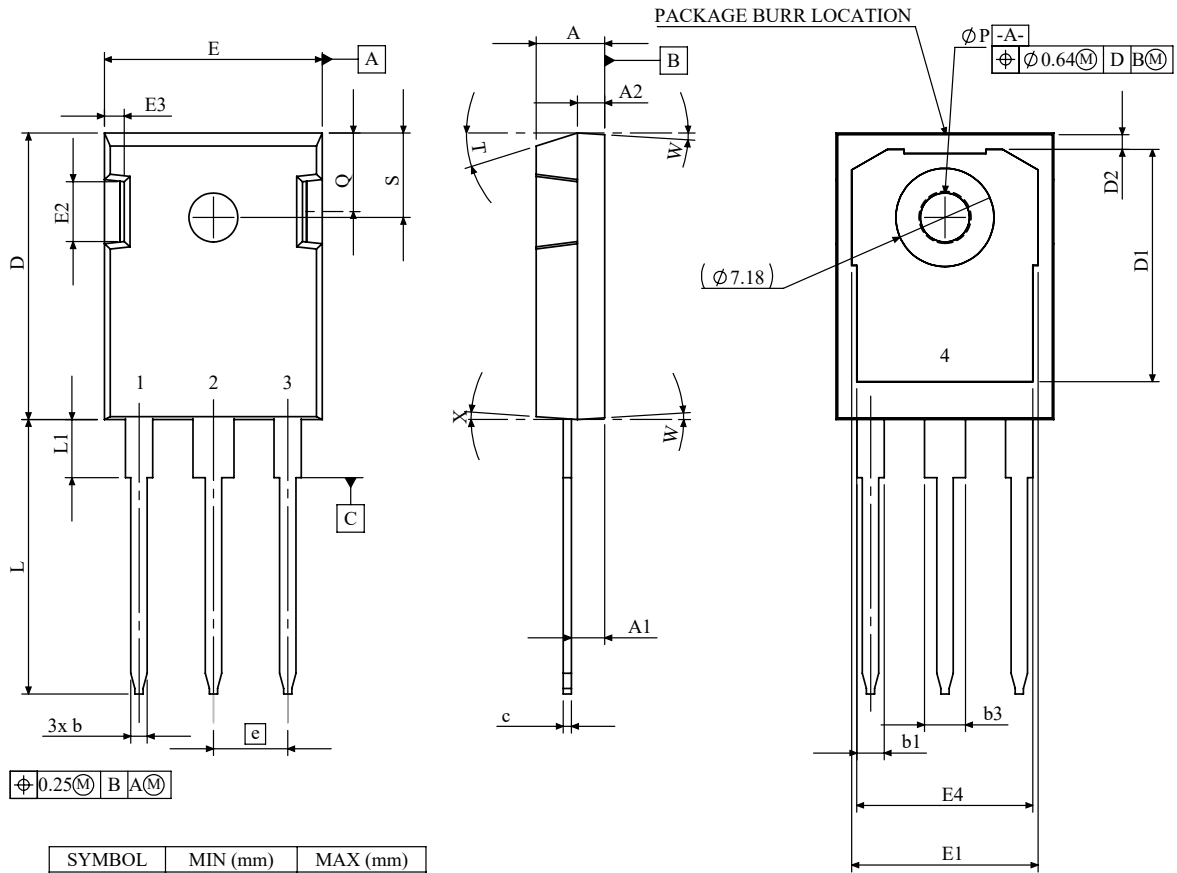
Figure 29. Clamped Inductive Switching Test Circuit

Note (3): Turn-off and Turn-on switching energy and timing values measured using SiC MOSFET Body Diode as shown above.



Package Dimensions

Package: TO-247-3



$\phi 0.25(M)$ B A(M)

SYMBOL	MIN (mm)	MAX (mm)
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b	1.07	1.33
b1	1.91	2.41
b3	2.87	3.38
c	0.55	0.68
D	20.8	21.1
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.1	14.15
E2	3.68	5.1
E3	1	1.9
E4	12.38	13.43
e	5.44 BSC	
L	19.81	20.32
L1	4.1	4.4
ϕP	3.51	3.65
Q	5.49	6
S	6.04	6.3
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

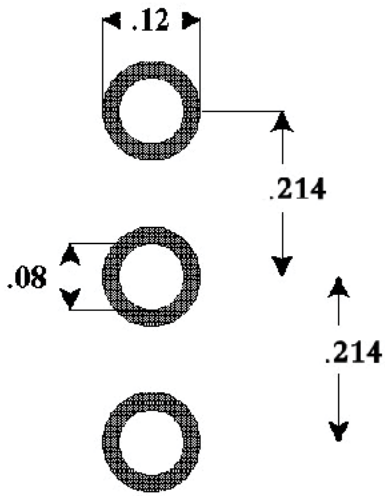
1	GATE
2	DRAIN
3	SOURCE
4	DRAIN

NOTES:

1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. BURR OR MOLD FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS



Recommended Solder Pad Layout



Part Number	Package	Marking
E3M0280090	TO-247-3	E3M0280090D



Revision History

Current Revision	Date of Release	Description of Changes
1.0	December-2023	Updated Wolfspeed branding, package drawing, and solder pad layout



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REACH Compliance

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